

UNIU79.022ADS



PATENT

Applicant : Yuji Okawa
Appl. No. : 10/809,566
Filed : March 25, 2004
For : WAFER BACK SURFACE
TREATING METHOD AND DICING
SHEET ADHERING APPARATUS
Examiner : Thanhha S Pham
Group Art Unit : 2813

CERTIFICATE OF MAILING

I hereby certify that this correspondence and all marked attachments are being deposited with the United States Postal Service as first-class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on

January 12, 2006

(Date)


Katsuhiro Arai, Reg. No. 43,315

RESPONSE TO RESTRICTION REQUIREMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

This is in response to the communication from the Examiner mailed December 19, 2005. In response to the restriction requirement set forth in the communication, Applicant elects to prosecute Group I, Claims 1-10, drawn to a method of treating a wafer back surface. Applicant further elects Species 2 drawn to a wafer back surface treating with blowing ozone to which the claims shall be restricted if no generic claim is finally held to be allowable. Claims 1, 3, 6, and 8 read on the elected species, and claim 1 is generic. This election is made without traverse.


No fees are believed due for the present Amendment, however, should any fees be due, please charge them to our deposit account No. 11-1410.

Respectfully submitted,

KNOBBE, MARTENS, OLSON & BEAR, LLP

Dated: January 12, 2006

By:


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